

SN74LV139A Dual 2-Line to 4-Line Decoders/Demultiplexers

1 Features

- 2V to 5.5V V_{CC} operation
- Maximum t_{pd} of 7.5ns at 5V
- Support mixed-mode voltage operation on all ports
- Designed specifically for high-speed memory decoders and data-transmission systems
- Incorporate two enable inputs to simplify cascading and/or data reception
- I_{off} supports partial-power-down mode operation
- Latch-up performance exceeds 250mA per JESD 17

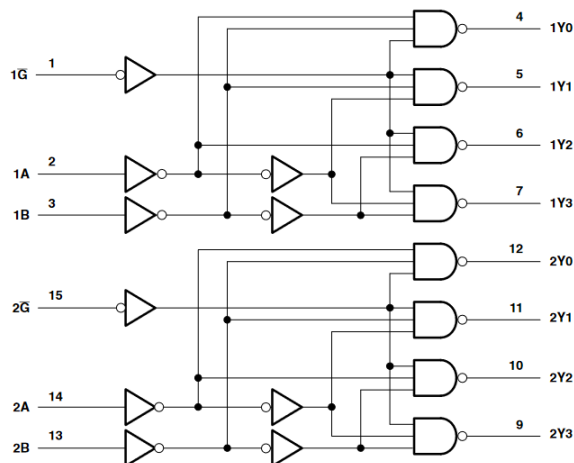
2 Description

The SN74LV139A devices are dual 2-line to 4-line decoders/demultiplexers designed for 2V to 5.5V V_{CC} operation.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
SN74LV139A	D (SOIC, 16)	9.90 mm × 6mm	9.90 mm × 3.91 mm
	DB (SSOP, 16)	6.20mm × 7.8mm	6.20 mm × 5.30 mm
	DGV (TVSOP, 16)	3.6mm × 6.4mm	3.6mm × 4.4mm
	PW (TSSOP, 16)	5.00mm × 6.4mm	5.00 mm × 4.40 mm
	NS (SOP, 16)	10.2mm × 7.8mm	10.20 mm × 5.30 mm
	RGY (VQFN, 16)	4.00 mm × 3.50 mm	4.00 mm × 3.50 mm

- (1) For more information, see [Mechanical, Packaging, and Orderable Information](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



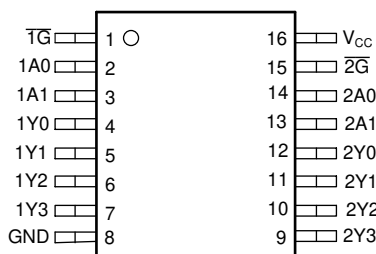
Logic Diagram (Positive Logic)



Table of Contents

1 Features	1	6.2 Functional Block Diagram.....	8
2 Description	1	6.3 Device Functional Modes.....	8
3 Pin Configuration and Functions	3	7 Application and Implementation	10
4 Specifications	4	7.1 Power Supply Recommendations.....	10
4.1 Absolute Maximum Ratings.....	4	7.2 Layout.....	10
4.2 ESD Ratings.....	4	8 Device and Documentation Support	12
4.3 Recommended Operating Conditions.....	4	8.1 Documentation Support.....	12
4.4 Thermal Information.....	5	8.2 Receiving Notification of Documentation Updates....	12
4.5 Electrical Characteristics.....	5	8.3 Support Resources.....	12
4.6 Switching Characteristics, $V_{CC} = 2.5V \pm 0.2V$	6	8.4 Trademarks.....	12
4.7 Switching Characteristics, $V_{CC} = 3.3V \pm 0.3V$	6	8.5 Electrostatic Discharge Caution.....	12
4.8 Switching Characteristics, $V_{CC} = 5V \pm 0.5V$	6	8.6 Glossary.....	12
4.9 Operating Characteristics.....	6	9 Revision History	12
5 Parameter Measurement Information	7	10 Mechanical, Packaging, and Orderable Information	12
6 Detailed Description	8		
6.1 Overview.....	8		

3 Pin Configuration and Functions



SN74LV139A D, DB, DGV, NS, OR PW Package; 16-Pin SOIC, SSOP, TVSOP, SOP, or TSSOP(Top View)

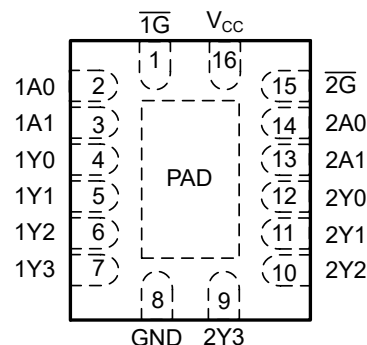


Figure 3-1. SN74LV139A RGY Package, 16-Pin VQFN

Table 3-1. Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	$\overline{1G}$	I	Channel 1, output enable, active low
2	$1A_0$	I	Channel 1, address select 0
3	$1A_1$	I	Channel 1, address select 1
4	$1Y_0$	O	Channel 1, output 0
5	$1Y_1$	O	Channel 1, output 1
6	$1Y_2$	O	Channel 1, output 2
7	$1Y_3$	O	Channel 1, output 3
8	GND	—	Ground
9	$2Y_3$	O	Channel 2, output 3
10	$2Y_2$	O	Channel 2, output 2
11	$2Y_1$	O	Channel 2, output 1
12	$2Y_0$	O	Channel 2, output 0
13	$2A_1$	I	Channel 2, address select 1
14	$2A_0$	I	Channel 2, address select 0
15	$\overline{2G}_0$	I	Channel 2, output enable, active low
16	V_{CC}	—	Positive supply

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		–0.5	7	V
V _I ⁽²⁾	Input voltage range		–0.5	7	V
V _O ⁽²⁾	Voltage range applied to any output in the high-impedance or power-off state		–0.5	7	V
V _O ⁽²⁾ ⁽³⁾	Output voltage range		–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		–20	mA
I _{OK}	Output clamp current	V _O < 0		–50	mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±25	mA
	Continuous current through V _{CC} or GND			±50	mA
T _{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.

4.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

4.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN74LV139A		UNIT
		MIN	MAX	
V _{CC}	Supply voltage	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5	V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7	
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7	
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7	
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5	V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.3	
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.3	
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.3	
V _I	Input voltage	0	5.5	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V	–50	mA
		V _{CC} = 2.3 V to 2.7 V	–2	
		V _{CC} = 3 V to 3.6 V	–6	
		V _{CC} = 4.5 V to 5.5 V	–12	

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN74LV138A		UNIT
		MIN	MAX	
I _{OL} Low-level output current	V _{CC} = 2 V		50	μA
	V _{CC} = 2.3 V to 2.7 V		2	mA
	V _{CC} = 3 V to 3.6 V		6	
	V _{CC} = 4.5 V to 5.5 V		12	
Δt/Δv Input transition rise or fall rate	V _{CC} = 2.3 V to 2.7 V		200	ns/V
	V _{CC} = 3 V to 3.6 V		100	
	V _{CC} = 4.5 V to 5.5 V		20	
T _A Operating free-air temperature		–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74LV139A						UNIT
		D (SOIC)	DB (SSOP)	DGV (TVSOP)	NS (SOP)	PW (TSSOP)	RGY (VQFN)	
		16 PINS						
R _{θJA}	Junction-to-ambient thermal resistance	73	82	120	64	108	39	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	SN74LV139A			UNIT
				MIN	TYP	MAX	
V _{OH}	High-Level Output Voltage	I _{OH} = −50μA	2V to 5.5V	V _{CC} − 0.1			V
		I _{OH} = −2mA	2.3V	2			
		I _{OH} = −6mA	3V	2.48			
		I _{OH} = −12mA	4.5V	3.8			
V _{OL}	Low-Level Output Voltage	I _{OL} = 50μA	2V to 5.5V	0.1			V
		I _{OL} = 2mA	2.3V	0.4			
		I _{OL} = 6mA	3V	0.44			
		I _{OL} = 12mA	4.5V	0.55			
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	±1			μA
I _{CC}	Supply Current	V _I = V _{CC} or GND, I _O = 0	5.5V	20			μA
I _{off}	Input/Output Power-Off Leakage Current	V _I or V _O = 0 to 5.5V	0	5			μA
C _i	Input Capacitance	V _I = V _{CC} or GND	3.3V	1.9			pF

4.6 Switching Characteristics, $V_{CC} = 2.5V \pm 0.2V$

over recommended operating free-air temperature range, $V_{CC} = 2.5V \pm 0.2V$ (unless otherwise noted) (see [Load Circuits and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ C$			SN74LV139A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	$C_L = 15pF$		7.7 ⁽¹⁾	17.6 ⁽¹⁾	1	21	ns
	$\overline{G}$				7.4 ⁽¹⁾	15.8 ⁽¹⁾	1	19	
t_{pd}	A or B	Y	$C_L = 50pF$		10.2	22.5	1	26.5	ns
	$\overline{G}$				9.9	20.2	1	24	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

4.7 Switching Characteristics, $V_{CC} = 3.3V \pm 0.3V$

over recommended operating free-air temperature range, $V_{CC} = 3.3V \pm 0.3V$ (unless otherwise noted) (see [Load Circuits and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ C$			SN74LV139A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	$C_L = 15pF$		5.3 ⁽¹⁾	11 ⁽¹⁾	1	13	ns
	$\overline{G}$				5.1 ⁽¹⁾	9.2 ⁽¹⁾	1	11	
t_{pd}	A or B	Y	$C_L = 50pF$		7.3	14.5	1	16.5	ns
	$\overline{G}$				7	12.7	1	14.5	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

4.8 Switching Characteristics, $V_{CC} = 5V \pm 0.5V$

over recommended operating free-air temperature range, $V_{CC} = 5V \pm 0.5V$ (unless otherwise noted) (see [Load Circuits and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ C$			SN74LV139A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	$C_L = 15pF$		3.7 ⁽¹⁾	7.2 ⁽¹⁾	1	8.5	ns
	$\overline{G}$				3.5 ⁽¹⁾	6.3 ⁽¹⁾	1	7.5	
t_{pd}	A or B	Y	$C_L = 50pF$		5.2	9.2	1	10.5	ns
	$\overline{G}$				4.9	8.3	1	9.5	

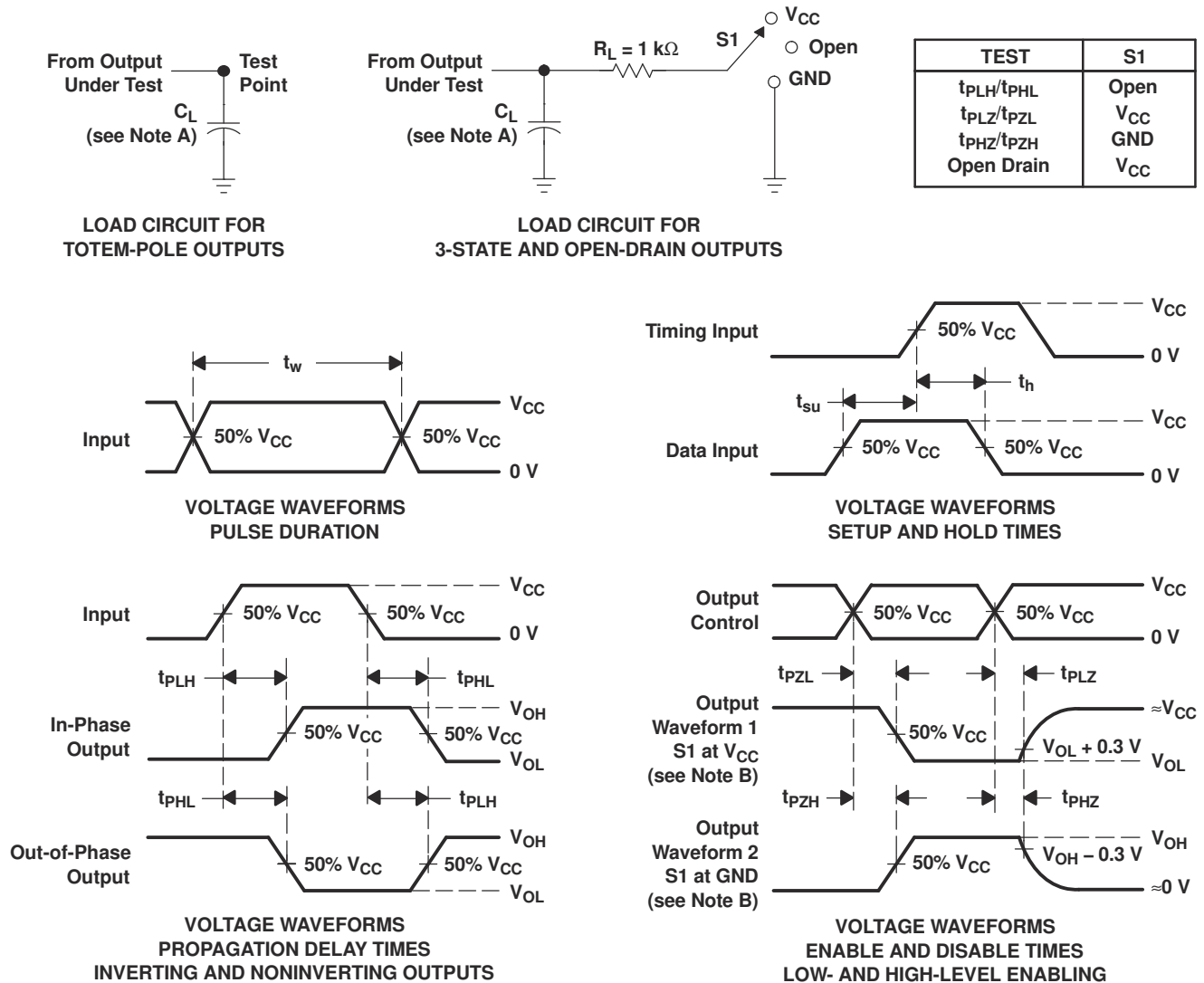
(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

4.9 Operating Characteristics

$T_A = 25^\circ C$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50 pF, f = 10 MHz$	3.3 V	17.3	pF
			5 V	18.2	

5 Parameter Measurement Information



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 5-1. Load Circuits and Voltage Waveforms

6 Detailed Description

6.1 Overview

The SNx4LV139A devices are 3-line to 8-line decoders/demultiplexers designed for 2 V to 5.5 V V_{CC} operation.

These devices are designed for high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The 'LV139A devices comprise two individual 2-line to 4-line decoders in a single package. The active-low enable ($\overline{G}$) input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

6.2 Functional Block Diagram

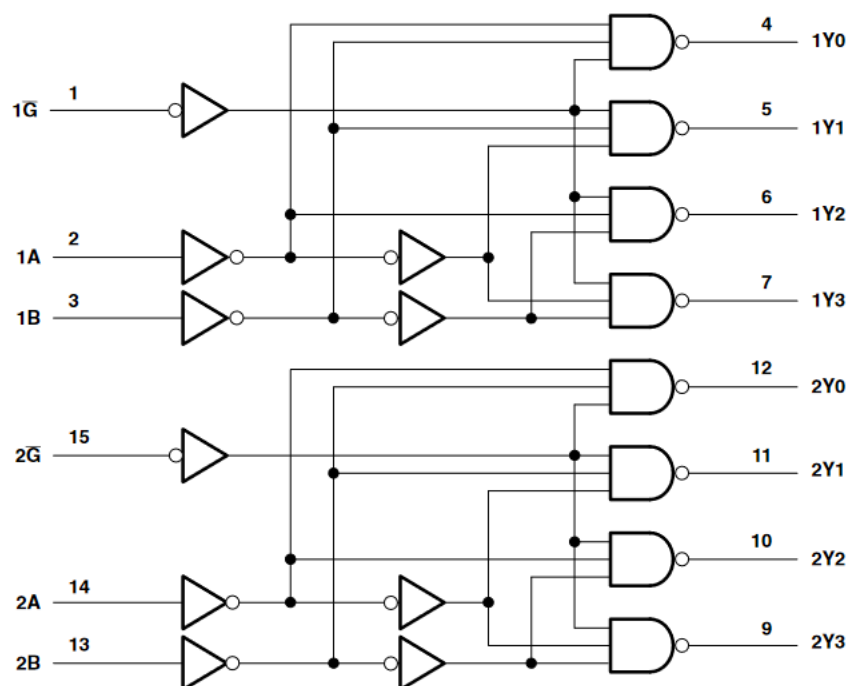


Figure 6-1. Logic Diagram (Positive Logic)

6.3 Device Functional Modes

Function Table

INPUTS			OUTPUTS			
$\overline{G}$	SELECT		Y0	Y1	Y2	Y3
	B	A				
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H

Function Table (continued)

INPUTS			OUTPUTS			
G̅	SELECT					
	B	A	Y0	Y1	Y2	Y3
L	H	H	H	H	H	L

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A $0.1\mu\text{F}$ capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The $0.1\mu\text{F}$ and $1\mu\text{F}$ capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

- Bypass capacitor placement
 - Place near the positive supply terminal of the device
 - Provide an electrically short ground return path
 - Use wide traces to minimize impedance
 - Keep the device, capacitors, and traces on the same side of the board whenever possible
- Signal trace geometry
 - 8mil to 12mil trace width
 - Lengths less than 12cm to minimize transmission line effects
 - Avoid 90° corners for signal traces
 - Use an unbroken ground plane below signal traces
 - Flood fill areas around signal traces with ground
 - For traces longer than 12cm
 - Use impedance controlled traces
 - Source-terminate using a series damping resistor near the output
 - Avoid branches; buffer signals that must branch separately

7.2.2 Layout Example

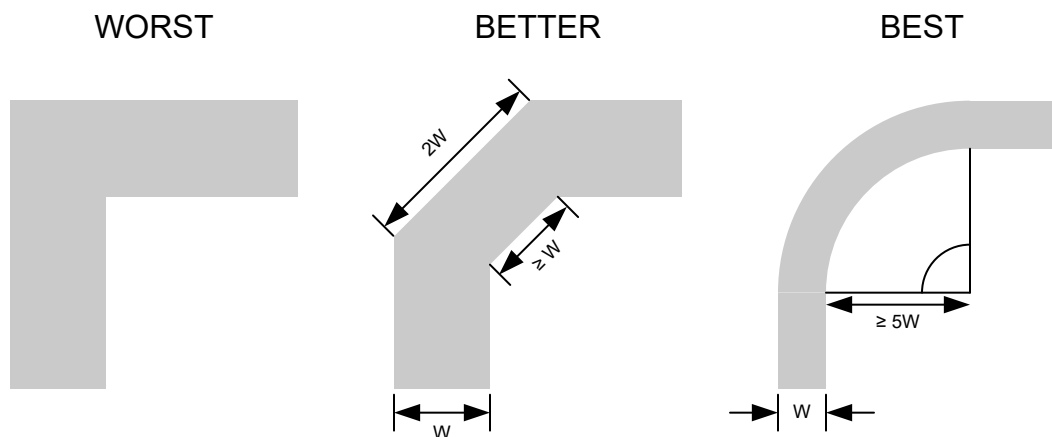


Figure 7-1. Example Trace Corners for Improved Signal Integrity

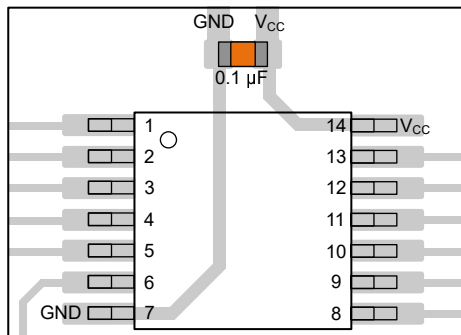


Figure 7-2. Example Bypass Capacitor Placement for TSSOP and Similar Packages

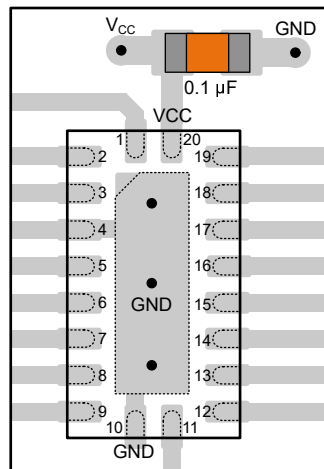


Figure 7-3. Example Bypass Capacitor Placement for WQFN and Similar Packages

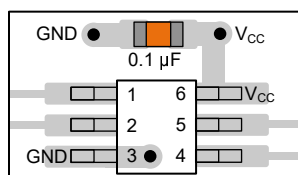


Figure 7-4. Example Bypass Capacitor Placement for SOT, SC70 and Similar Packages

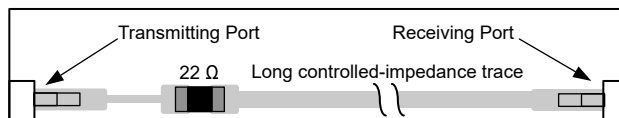


Figure 7-5. Example Damping Resistor Placement for Improved Signal Integrity

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Documentation Support

8.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and \$C_{pd}\$ Calculation application report](#)
- Texas Instruments, [Designing With Logic application report](#)
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application report](#)

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

Changes from Revision I (April 2005) to Revision J (December 2024)	Page
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Deleted references to machine model.....	4

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV139AD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	LV139A
SN74LV139ADBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139ADBR.A	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139ADR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139ADR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139ANSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV139A
SN74LV139ANSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV139A
SN74LV139ANSRE4	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV139A
SN74LV139APW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	LV139A
SN74LV139APWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139APWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139APWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139APWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139APWRG4.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139APWRG4.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV139A
SN74LV139ARGYR	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV139A
SN74LV139ARGYR.A	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LV139A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

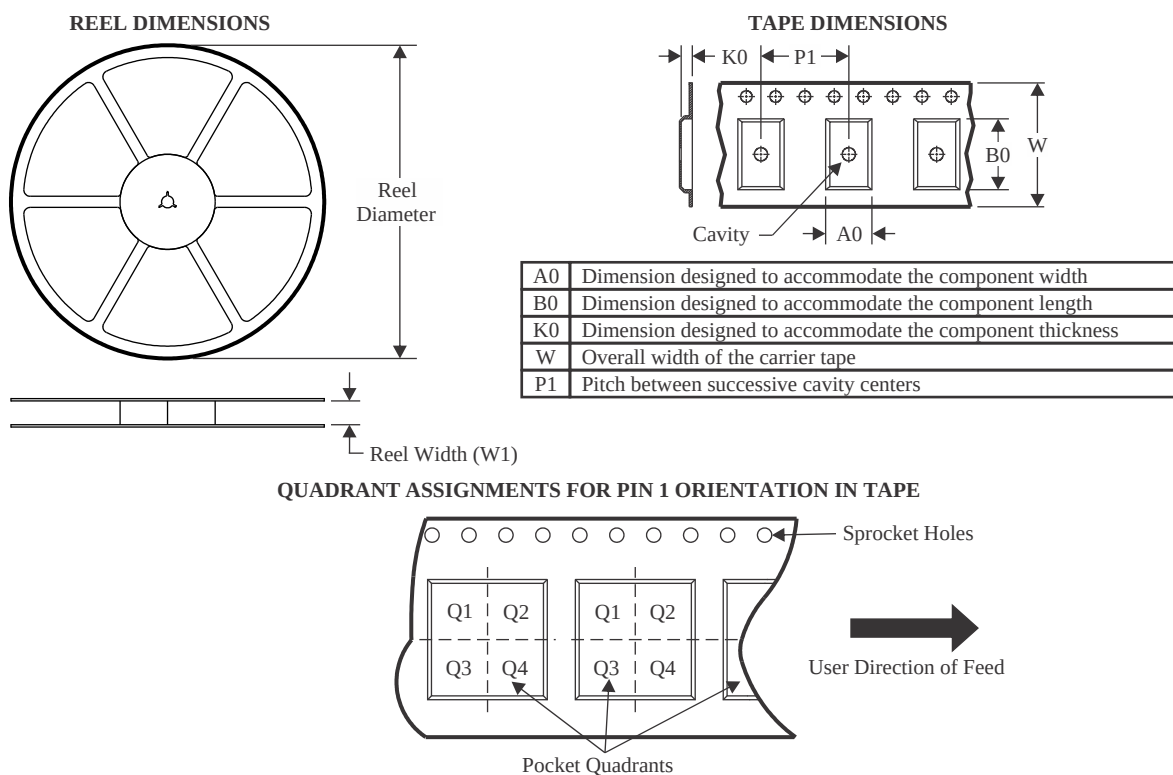
(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

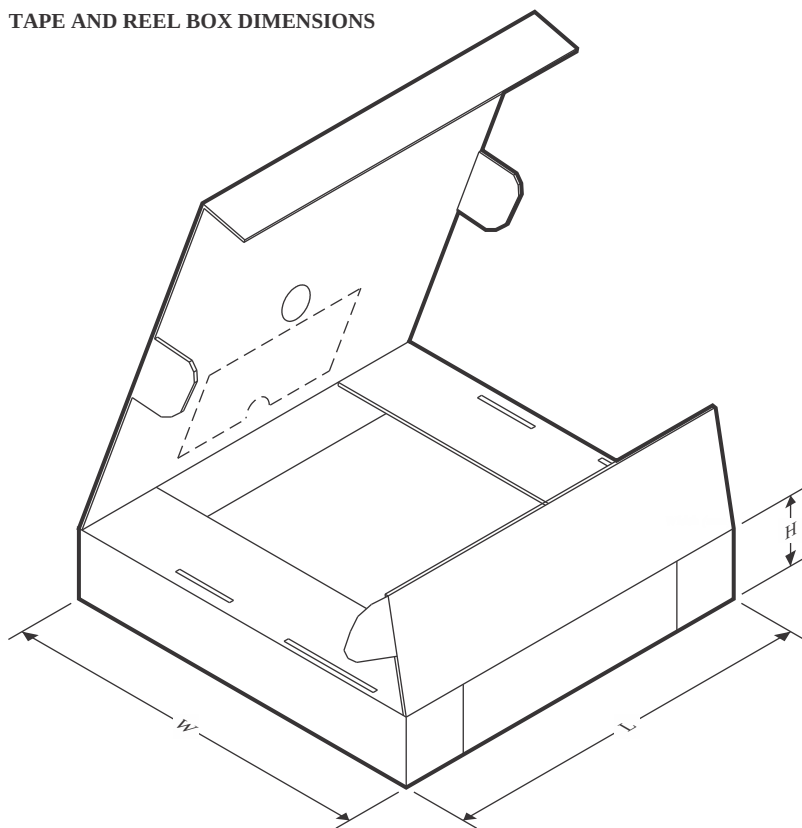
TAPE AND REEL INFORMATION



*All dimensions are nominal

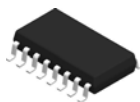
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV139ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV139ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV139ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV139APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV139APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV139ARGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV139ADBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74LV139ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LV139ANSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74LV139APWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LV139APWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LV139ARGYR	VQFN	RGY	16	3000	353.0	353.0	32.0

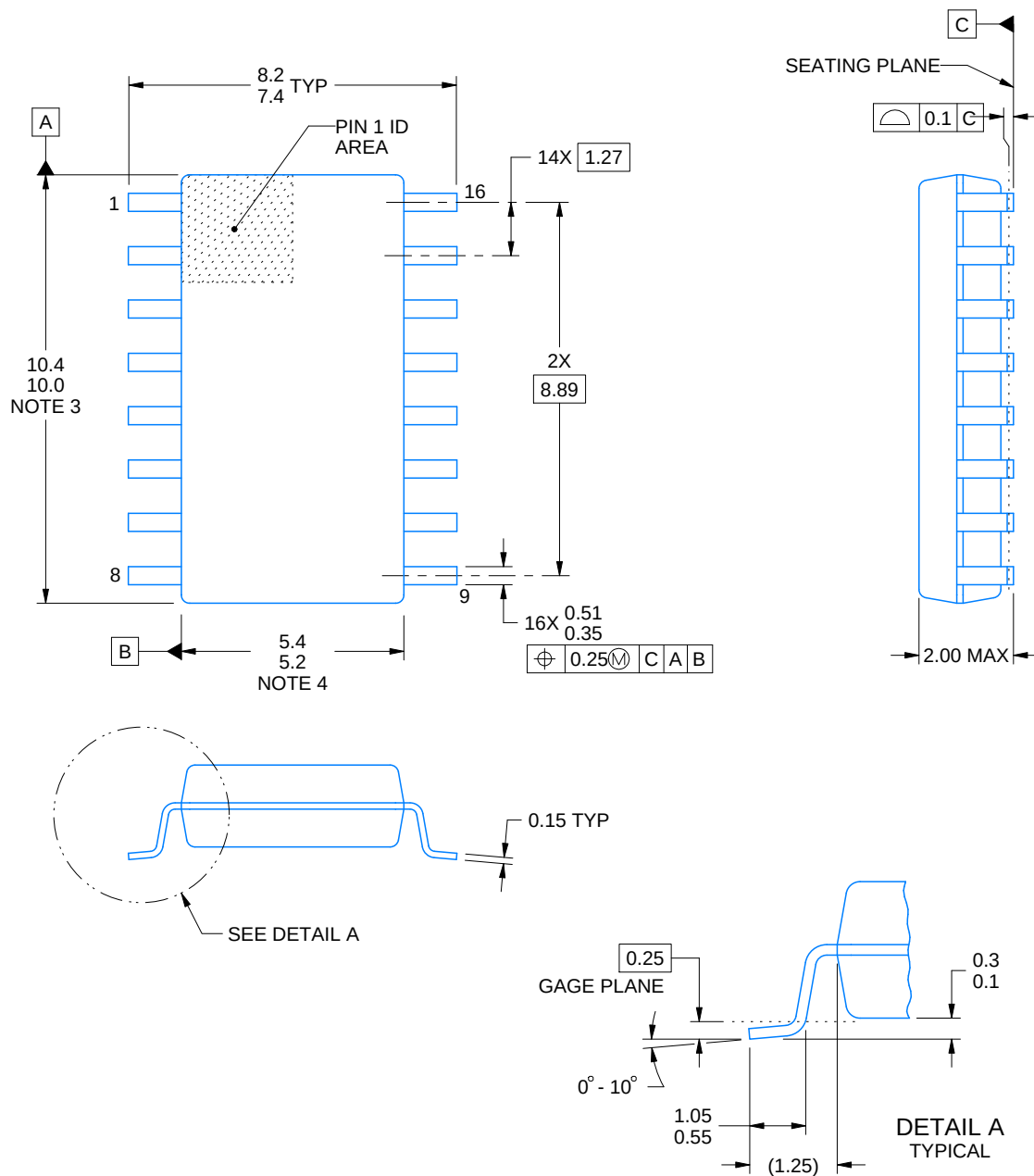


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

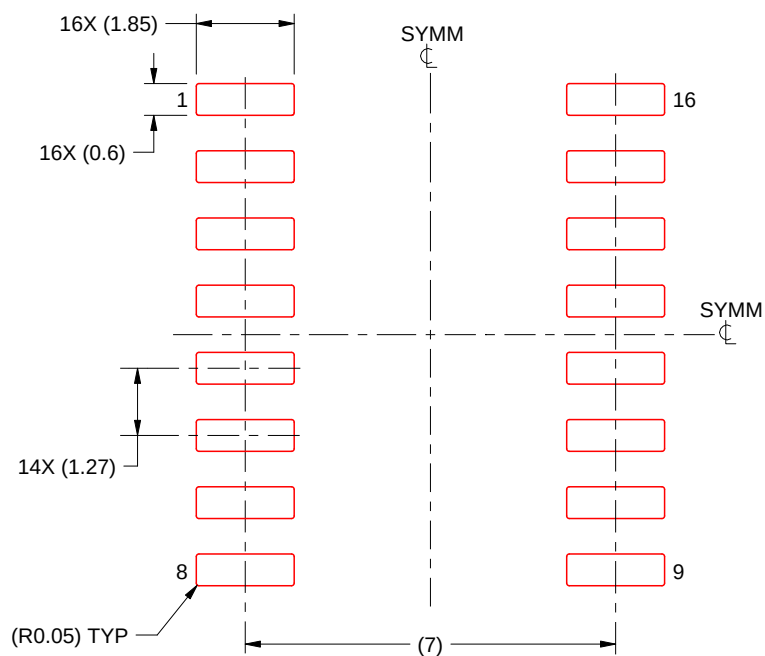
SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

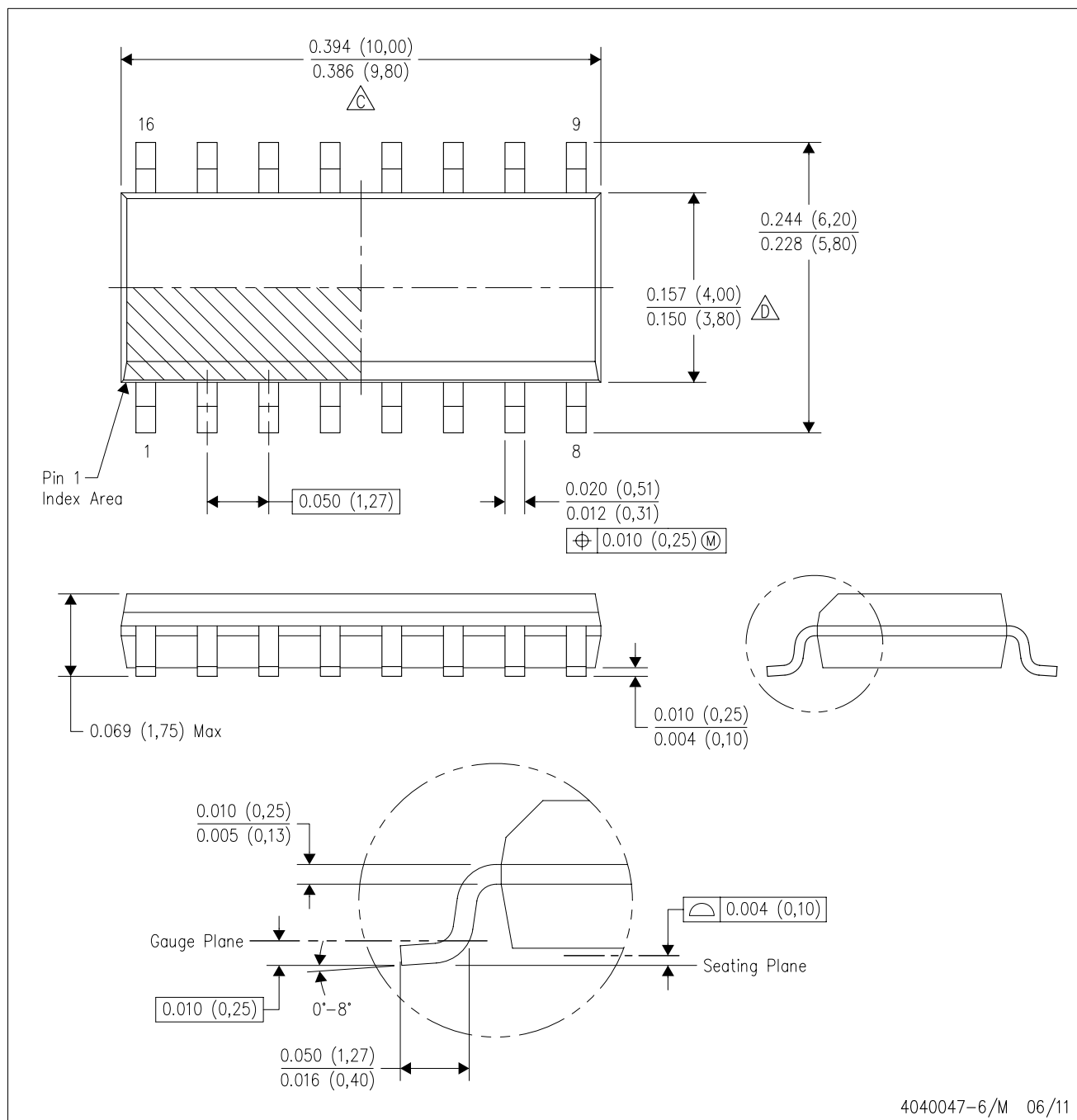
4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

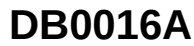
PLASTIC SMALL OUTLINE



4040047-6/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



SSOP - 2 mm max height

Technical drawing of a 16-pin connector, showing top, side, and detail views.

Top View:

- Overall width: 8.2 TYP, 7.4
- Overall height: 6.5, 5.9 (NOTE 3)
- Pin 1 Index Area: 5.6, 5.0 (NOTE 4)
- Pin 16 location: 16
- Pin 9 location: 9
- Pin 14 location: 14X 0.65
- Pin 2 location: 2X 4.55
- Pin 16X location: 16X 0.38, 0.22
- Feature Control Frame: $\oplus$ 0.1 M C A B

Side View:

- Seating Plane: Indicated by a vertical line and arrow.
- Feature Control Frame: C 0.1 C

Detail A (Typical):

- Feature Control Frame: 0.25
- Gage Plane: Indicated by a horizontal line and arrow.
- Angle: $0^\circ - 8^\circ$
- Dimensions: 0.95, 0.55, 2 MAX, 0.05 MIN

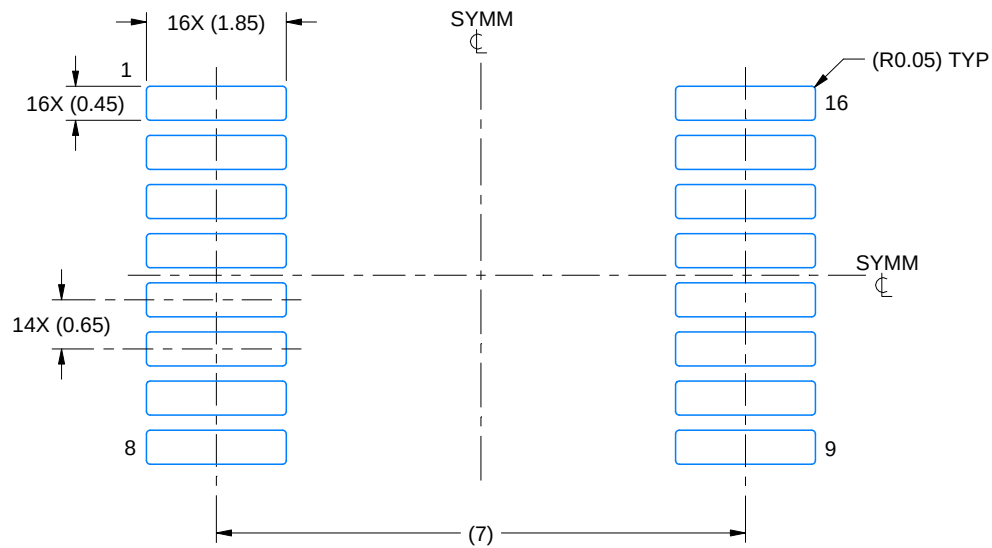
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

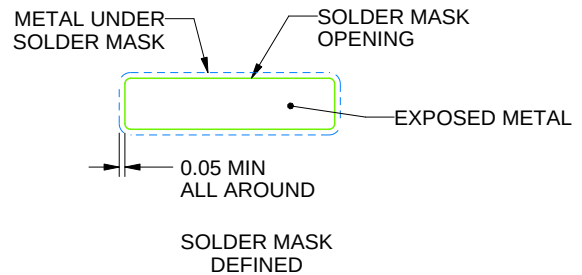
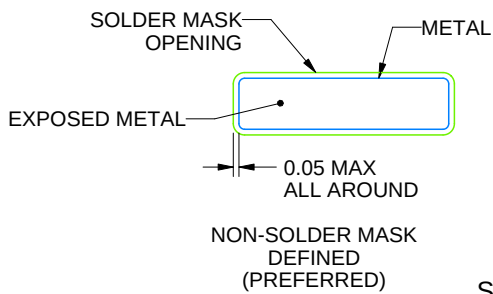
DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

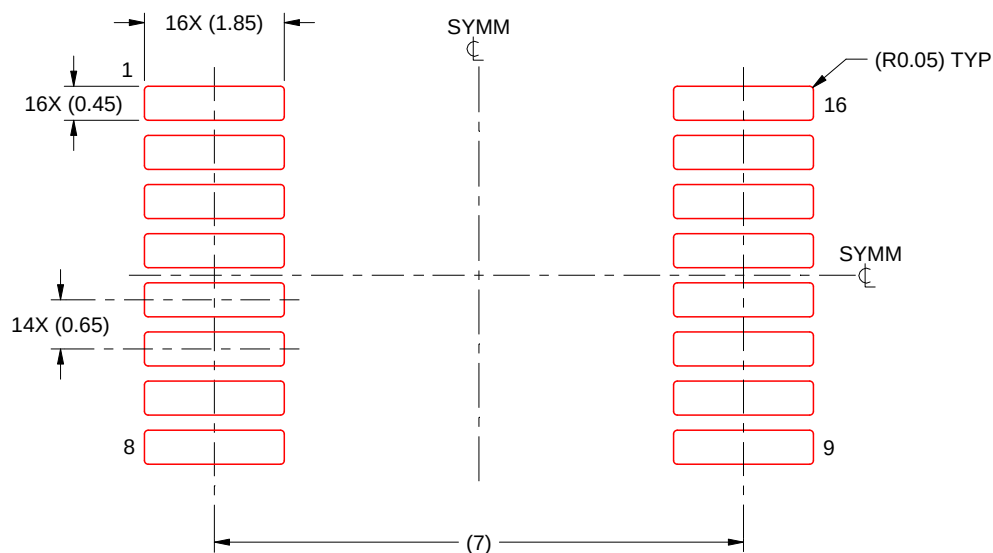
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

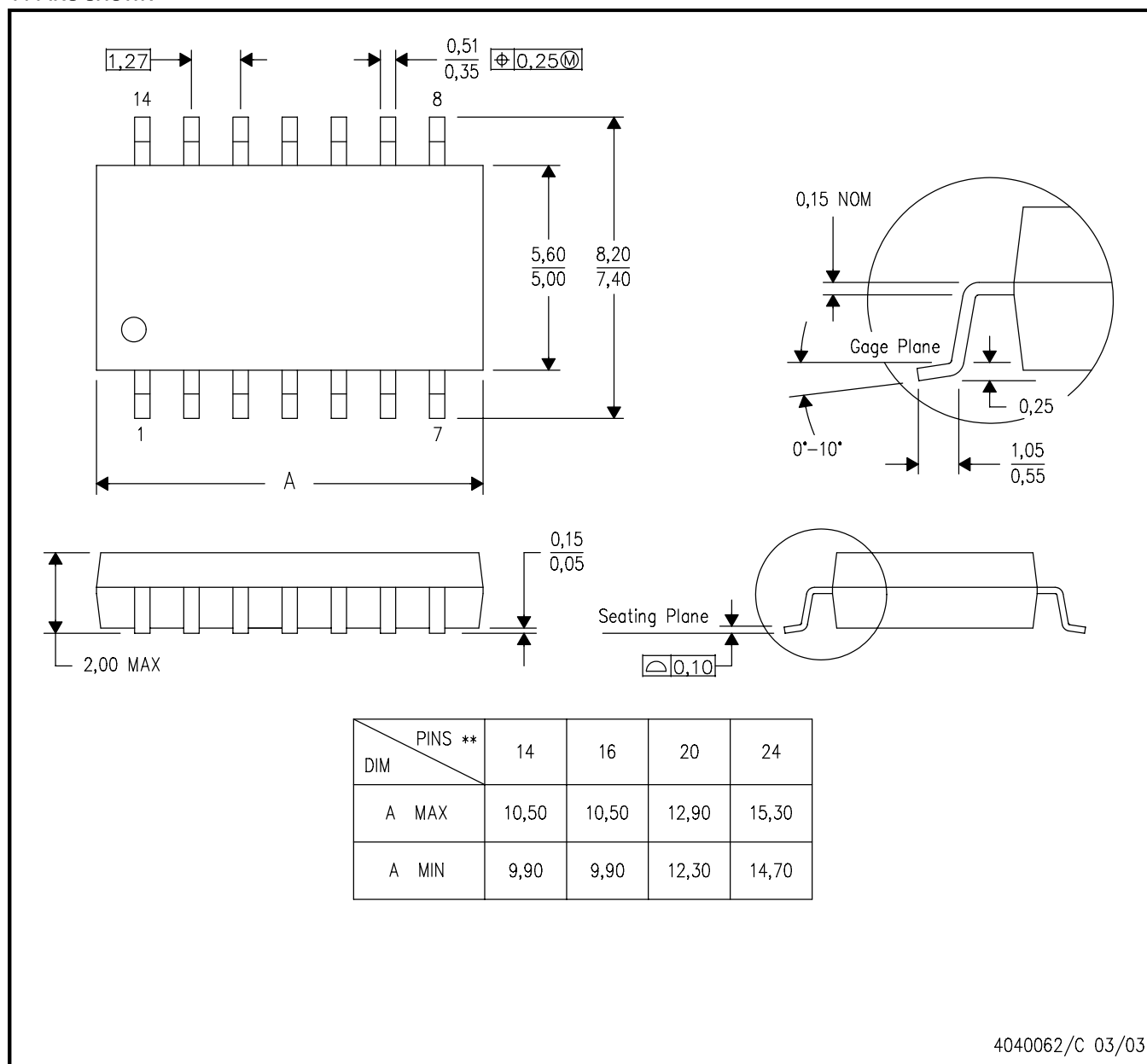
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

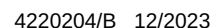


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



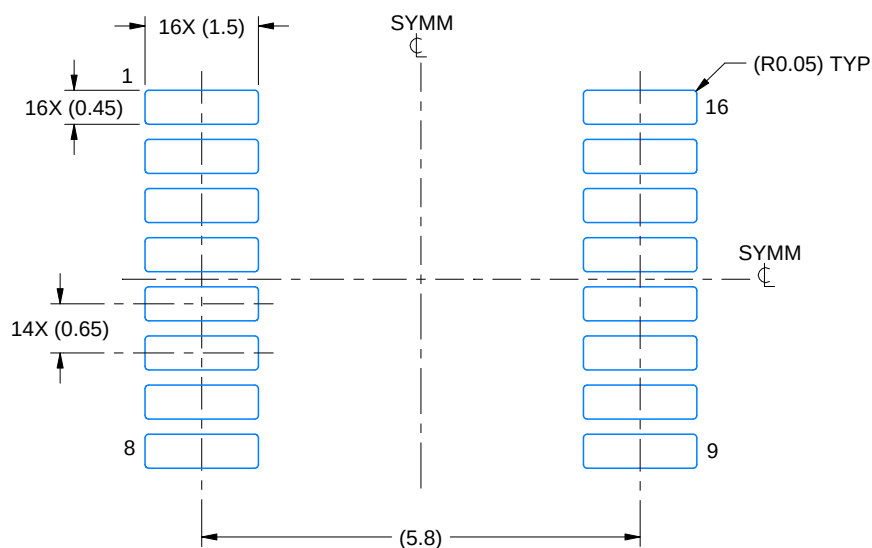
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

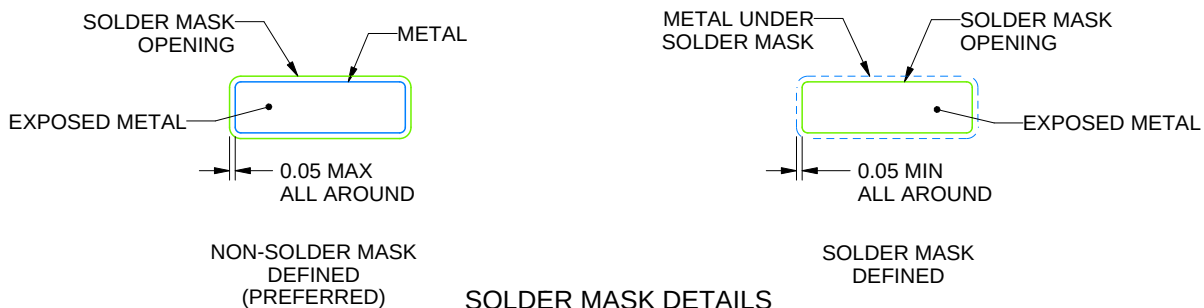
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

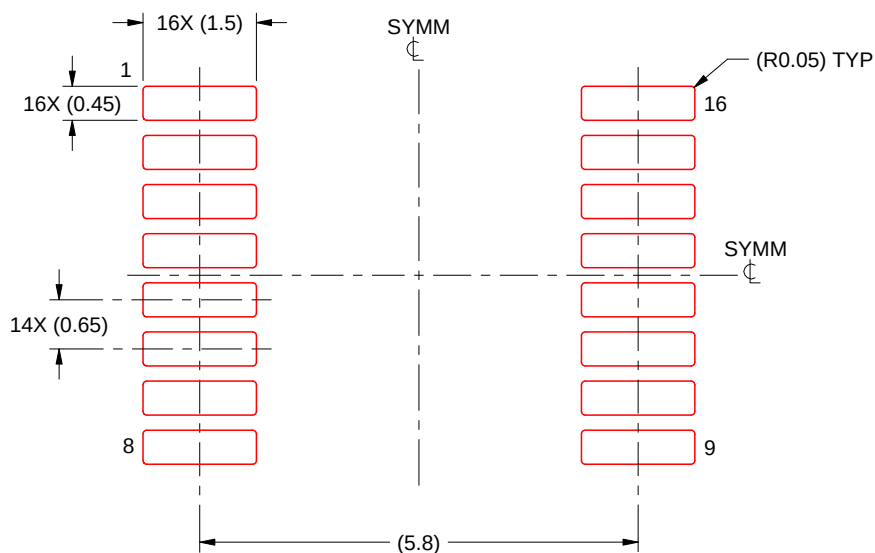
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

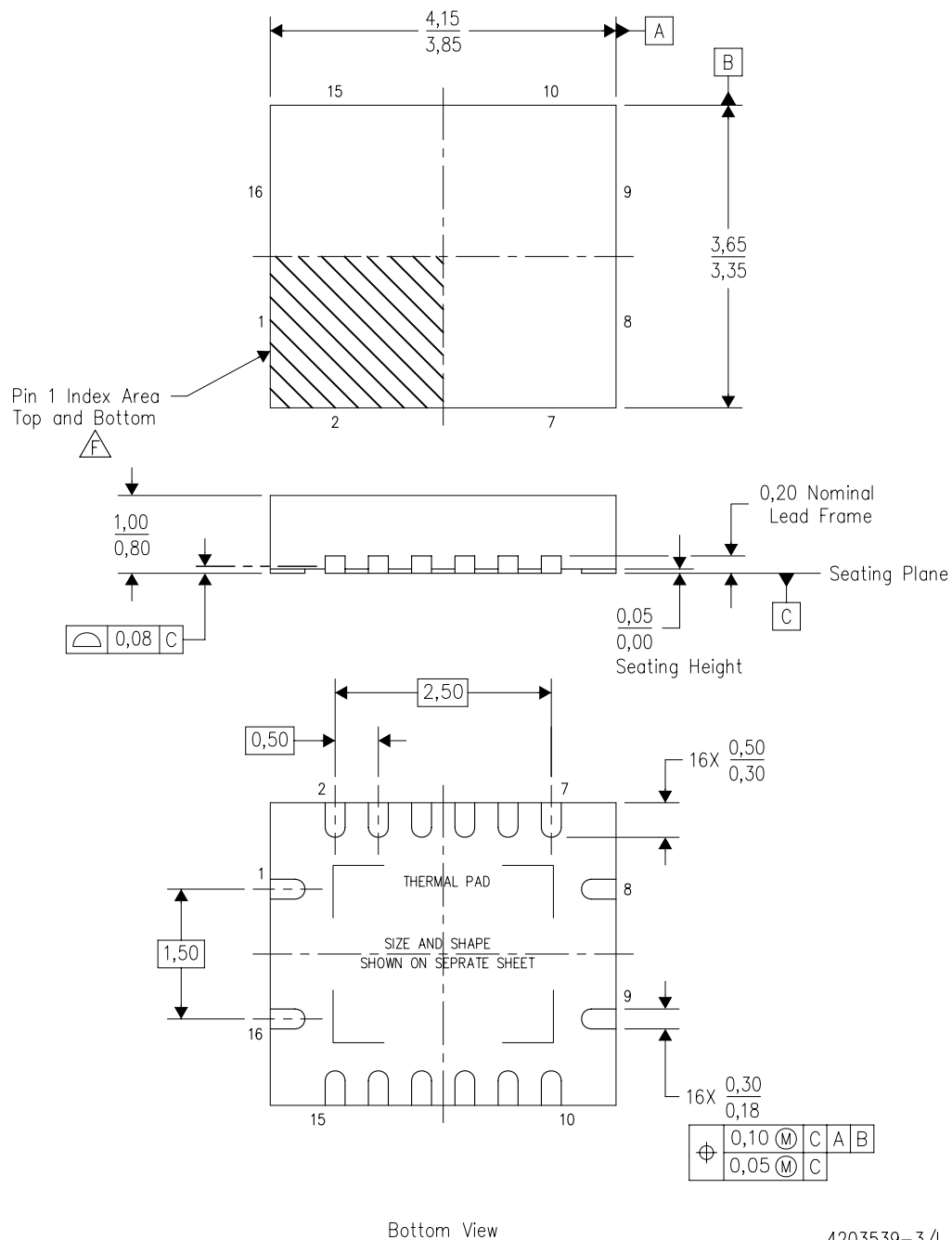
4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-3/I 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

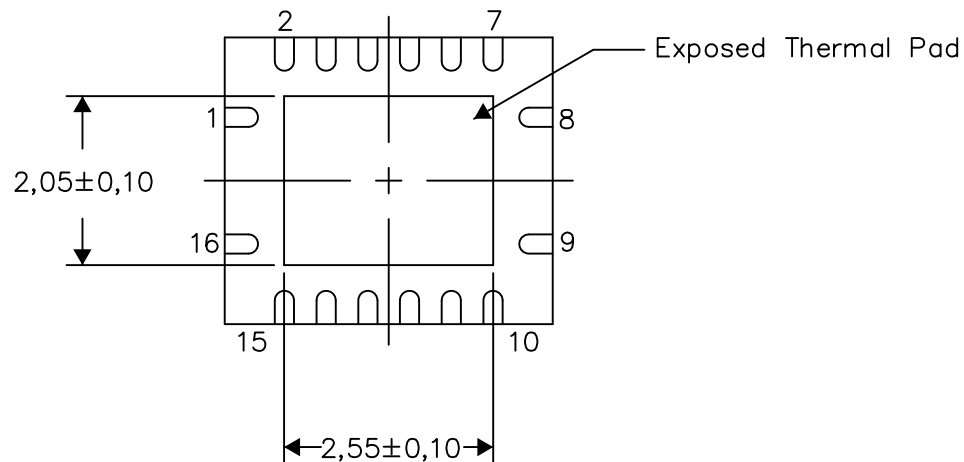
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

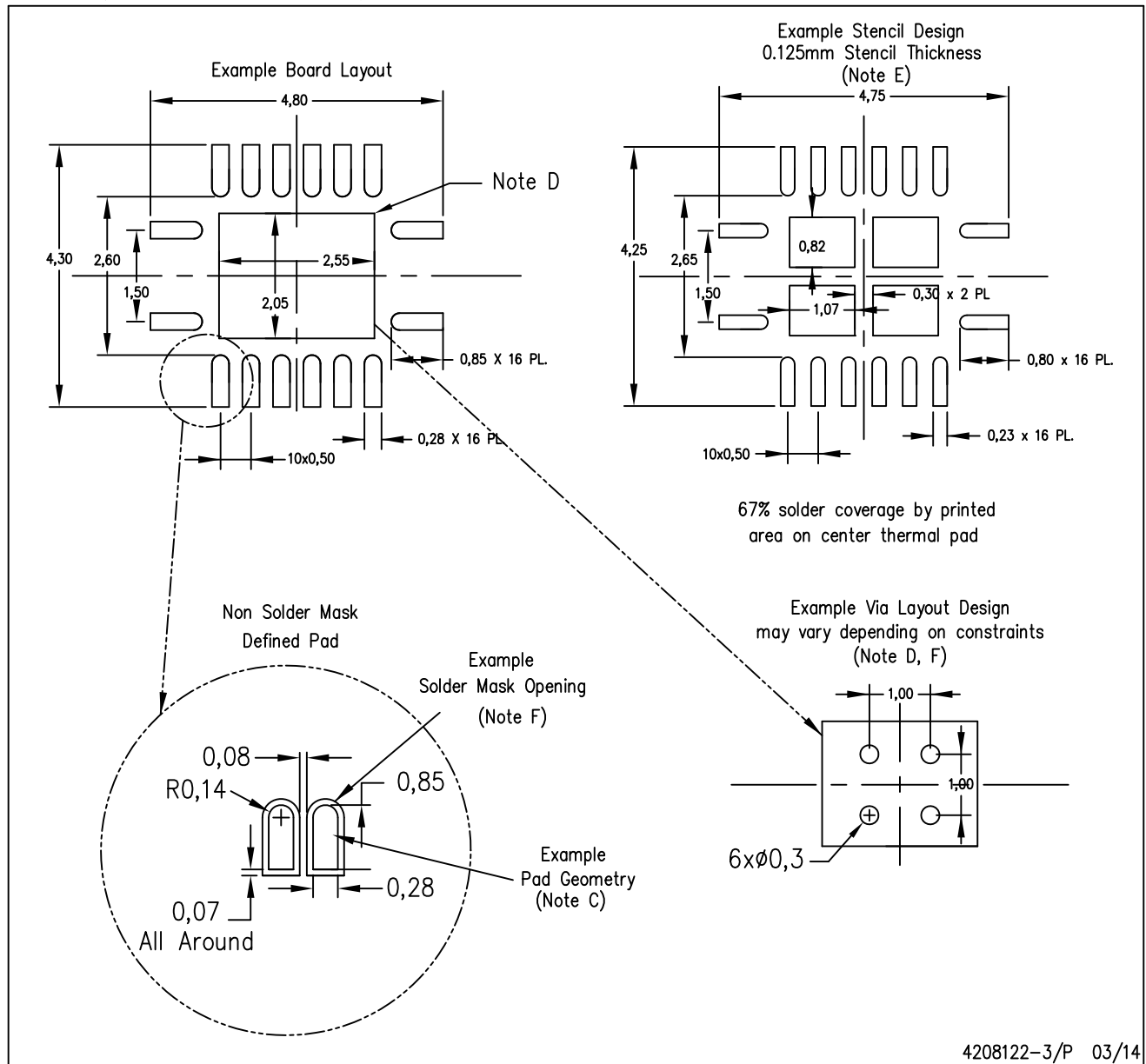
Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated